

MA2C029W

Silicon epitaxial planar type

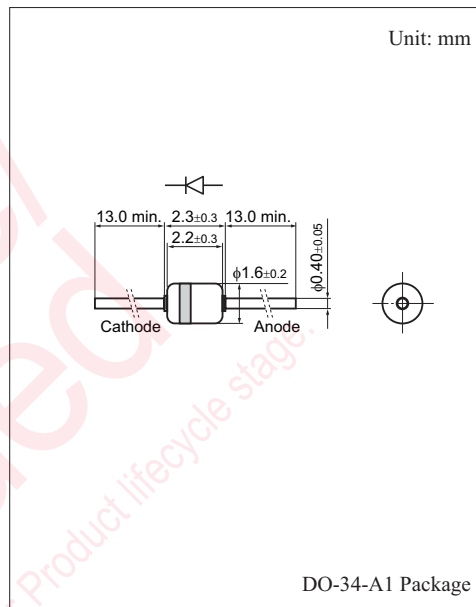
For reduced voltage and temperature compensation

■ Features

- High reliability achieved through combination of a planar type chip and glass sealing structure
- Easy mounting because of employing DO-35 (DHD) envelope
- Extremely small reverse current I_R
- Large power dissipation P_D
- Wide forward voltage V_F range

■ Absolute Maximum Ratings $T_a = 25^\circ\text{C}$

Parameter	Symbol	Rating	Unit
Reverse voltage	V_R	6	V
Peak forward current	I_{FM}	100	mA
Power dissipation	P_D	150	mW
Junction temperature	T_j	150	$^\circ\text{C}$
Storage temperature	T_{stg}	-55 to +150	$^\circ\text{C}$



■ Electrical Characteristics $T_a = 25^\circ\text{C} \pm 3^\circ\text{C}^{*1}$

Parameter	Symbol	Conditions	Min	Typ	Max	Unit
Forward current	V_{F1}	$I_R = 10 \mu\text{A}$	0.77			V
	V_{F2}	$I_F = 3 \text{ mA}$		*2		
Reverse current	I_R	$V_R = 6 \text{ V}$			1.0	μA
Temperature coefficient of forward voltage *3	$-\Delta V_F / V_T$	$I_F = 3 \text{ mA}$		4.6		$\text{mV}/^\circ\text{C}$

Note) 1. Measuring methods are based on JAPANESE INDUSTRIAL STANDARD JIS C 7031 measuring methods for diodes.

2. *1: The temperature must be controlled 25°C for V_F measurement. V_F value measured at other temperature must be adjusted to $V_F (25^\circ\text{C})$

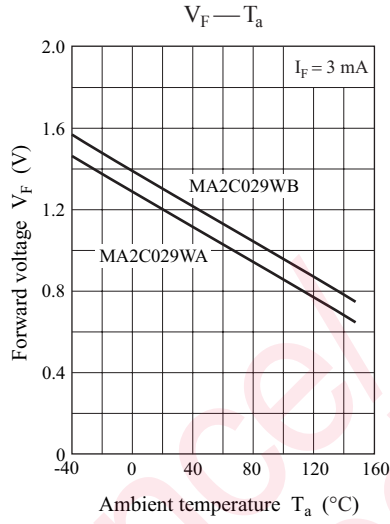
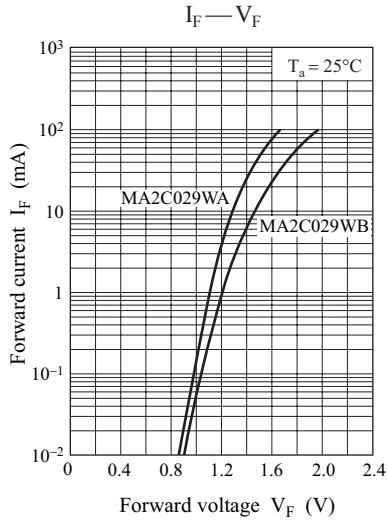
*2:

Type	$V_F (V)$
MA2C029WA	1.18 to 1.28
MA2C029WB	1.26 to 1.36

*3: $T_j = 25^\circ\text{C}$ to 150°C

■ Cathode Indication

Type No.	MA2C029WA	MA2C029WB
Color	Light blue	Brown



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